

**Amendments to the Claims:**

Claims 1 and 10 have been amended herein. Please note that all claims currently pending and under consideration in the referenced application are shown below. Please enter these claims as amended. This listing of claims will replace all prior versions and listings of claims in the application.

**Listing of Claims:**

1. (Currently Amended) A card comprising:  
a substrate formed from a strip of a plurality of substrates including a first side having a plurality of conductors, a second side having a plurality of contacts connected to at least one conductor of the plurality of conductors on the first side, at least one encapsulated semiconductor component on the first side, a molded peripheral portion laterally outwardly forming a periphery of the substrate, and at least one exposed connecting segment exposed at one of the periphery of the substrate and an intermediate region of the periphery of the substrate.
2. (Original) The card of claim 1, further comprising a notch in the periphery of the substrate to recess a portion of the exposed at least one connecting segment to a nonprotruding position.
3. (Previously Presented) The card of claim 1, wherein a portion of the at least one encapsulated semiconductor component abuts a portion of the molded peripheral portion along an interface thereof.
4. (Previously Presented) The card of claim 3, wherein an abutting portion of the molded peripheral portion is coplanar with the portion of the at least one encapsulated semiconductor component.

5. (Previously Presented) The card of claim 1, wherein encapsulation material of the at least one encapsulated semiconductor component and molding material of the molded peripheral portion comprise epoxy resin.

6. (Original) The card of claim 1, wherein the substrate comprises a reinforced organic polymer resin.

7. (Original) The card of claim 1, wherein the second side of the substrate is substantially exposed.

8. (Original) The card of claim 1, wherein the at least one semiconductor component comprises a memory component.

9. (Original) The card of claim 1, wherein the card comprises a memory card for digitally recording and retrievably storing photographic data in a digital camera.

10. (Currently Amended) A card comprising:  
a printed circuit substrate formed from a strip of a plurality of substrates including a first side having a plurality of conductors, a second side having a plurality of contacts connected to at least one conductor of the plurality of conductors on the first side, at least one encapsulated semiconductor component on the first side, a molded peripheral portion laterally outwardly forming a periphery of the substrate, and at least one exposed connecting segment exposed at one of the periphery of the substrate and an intermediate region of the periphery of the substrate.

11. (Previously Presented) The card of claim 10, further comprising a notch in the periphery of the printed circuit substrate to recess a portion of the at least one exposed connecting segment to a nonprotruding position.

12. (Previously Presented) The card of claim 10, wherein a portion of the at least one encapsulated semiconductor component abuts a portion of the molded peripheral portion along an interface thereof.

13. (Previously Presented) The card of claim 12, wherein an abutting portion of the molded peripheral portion is substantially coplanar with the portion of the at least one encapsulated semiconductor component.

14. (Original) The card of claim 10, wherein the printed circuit substrate comprises a reinforced organic polymer resin.

15. (Original) The card of claim 10, wherein the second side of the printed circuit substrate is substantially exposed.

16. (Original) The card of claim 10, wherein the at least one semiconductor component comprises a memory component.

17. (Previously Presented) The card of claim 10, wherein the card comprises a memory card for digitally recording and retrievably storing photographic data in a digital camera.

18. (Withdrawn) A method for fabricating a card having a substrate having a circuit side and a back side, the substrate generally separated from a surrounding frame by a peripheral opening spanned by at least one connecting segment between the substrate and the frame, the substrate having at least one electrical circuit and at least one connector for communicating between the at least one electrical circuit and an external circuit, comprising:  
clamping the substrate and the frame between a first plate and a second plate of a first molding assembly forming a first mold cavity for injecting a first material into the first mold cavity for molding a first plastic casting onto the circuit side of the substrate and encapsulating

the at least one electrical circuit while leaving a peripheral portion of the circuit side free of the first material, the first plastic casting having an exposed surface and clamping the frame, the substrate and the first plastic casting between a first plate and a second plate of a second molding assembly, at least a portion of the exposed surface of the first plastic casting compressed for sealingly engaging a portion of the back side of the substrate against the first plate of the second molding assembly, the first plate and the second plate of the second molding assembly forming a second mold cavity for injecting a second material into the second mold cavity for molding a second plastic casting surrounding the first plastic casting and enclosing the peripheral portion of the circuit side and an edge of the substrate, the second plastic casting having a peripheral outer edge; and singulating the substrate from the frame.

19. (Withdrawn) The method of claim 18, wherein the second molding assembly leaves the back side of the substrate substantially free of the second material.

20. (Withdrawn) The method of claim 18, further comprising:  
applying antifrash material to the back side of the substrate prior to clamping in the second molding assembly.

21. (Withdrawn) The method of claim 20, wherein the antifrash material comprises a film.

22. (Withdrawn) The method of claim 18, wherein the substrate has peripheral edges thereabout, and the at least one connecting segment comprises at least one connecting segment on each of two opposed peripheral edges of the substrate.

23. (Withdrawn) The method of claim 18, wherein the at least one electrical circuit includes at least one semiconductor component mounted on the circuit side.

24. (Withdrawn) The method of claim 18, wherein the first plastic casting and the second plastic casting each comprise an epoxy resin.

25. (Withdrawn) The method of claim 18, wherein the first material and the second material each comprise a different resin.

26. (Withdrawn) The method of claim 18, wherein the substrate comprises a reinforced organic polymer resin.

27. (Withdrawn) The method of claim 18, further comprising:  
subjecting the first plastic casting to a curing step prior to clamping in the second molding assembly.

28. (Withdrawn) The method of claim 18, further comprising:  
subjecting the second plastic casting to a curing step after removal from the second molding assembly.

29. (Withdrawn) The method of claim 18, wherein the first molding assembly and the second molding assembly each comprise transfer molds.

30. (Withdrawn) The method of claim 18, wherein the at least one connector is mounted on the back side of the substrate.

31. (Withdrawn) The method of claim 18, wherein the second molding assembly is configured to form the second plastic casting having an inner peripheral portion contiguous with the exposed surface of the first plastic casting, and an outer peripheral portion displaced from the exposed surface for attachment of a label covering an interface between the first plastic casting and the second plastic casting.

32. (Withdrawn) The method of claim 18, comprising:  
forming a notch in the second plastic casting during the molding thereof configured to enclose an exposed end of a connecting segment following singulation thereof.
33. (Withdrawn) The method of claim 32, wherein molding of the second plastic casting is performed by placing a pin in contact with the at least one connecting segment to form the notch.
34. (Withdrawn) The method of claim 32, wherein the singulation comprises cutting the connecting segment within the notch.
35. (Withdrawn) The method of claim 34, wherein the singulation comprises cutting the connecting segment with a cutter die.
36. (Withdrawn) The method of claim 18, wherein the second plastic casting is formed by compressing the frame and the substrate in the second molding assembly with the first plastic casting compressed for sealingly depressing the substrate to a displaced position relative to the frame.
37. (Withdrawn) The method of claim 36, wherein the second mold cavity provides for molding of laterally extending wings from a central portion of the peripheral outer edge of the second plastic casting, the wings extending outwardly beyond the peripheral outer edge.
38. (Withdrawn) The method of claim 36, wherein the displaced position provides encapsulation of the at least one connecting segment within the second plastic casting.
39. (Withdrawn) The method of claim 37, wherein singulating comprises cutting the wings and the at least one connecting segment from the second plastic casting along the peripheral outer edge thereof.

40. (Withdrawn) The method of claim 39, wherein the wings and the at least one connecting segment are cut from the second plastic casting with a saw.

41. (Withdrawn) The method of claim 39, wherein the wings and the at least one connecting segment are cut from the second plastic casting by stamping with a cutter die.

42. (Withdrawn) The method of claim 18, further comprising:  
removing extraneous hardened plastic attached to the first plastic casting.

43. (Withdrawn) The method of claim 18, further comprising:  
removing extraneous hardened plastic attached to the second plastic casting.

44. (Withdrawn) A method for fabricating a semiconductor card having a substrate having at least one circuit formed thereon and at least one connector from a plurality of spaced-apart substrates in a strip, the strip having a plurality of peripheral openings defining the plurality of substrates and a plurality of connecting segments attaching the plurality of substrates to the strip, the method comprising:  
mounting a card circuit on each substrate of the plurality of spaced-apart substrates, each card circuit comprising at least one semiconductor component and apparatus for communication between each card circuit and an external circuit;  
molding first plastic castings to the plurality of substrates using a first molding assembly comprising a plurality of mold cavities for forming a first plastic casting over each circuit while leaving a peripheral portion of each substrate uncovered and molding second plastic castings encapsulating the peripheral portions of the plurality of substrates;  
removing the strip from the second molding assembly; and  
severing the plurality of connecting segments to singulate individual semiconductor cards from the strip.

45. (Withdrawn) The method of claim 44, wherein each of the plurality of substrates has first and second planar sides, the card circuit mounted on the first side and including conductors connected to the apparatus mounted for communication on the second side.

46. (Withdrawn) The method of claim 44, wherein the apparatus for communication comprises conductive contacts.

47. (Withdrawn) The method of claim 45, wherein the first plastic casting is configured to be compressed by a first mold plate to force the second side of each substrate against a second mold plate during molding of the second plastic casting.

48. (Withdrawn) A method of fabricating a substrate having a circuit side and a back side, the substrate generally separated from a surrounding frame by a peripheral opening spanned by at least one connecting segment between the substrate and the frame, the substrate having an electrical circuit and at least one external connector for communicating between the electrical circuit and an external circuit, the method comprising:

placing the substrate and the frame in a first molding assembly for injecting a first material into a first mold cavity formed by first and second plates to mold a first plastic casting onto the circuit side of the substrate and to encapsulate the electrical circuit while leaving a peripheral portion of the circuit side uncovered, the first plastic casting having an exposed surface;

removing the frame, the substrate and the first plastic casting from the first molding assembly;

placing the frame, the substrate and the first plastic casting between first and second plates of a second molding assembly, the exposed surface of the first plastic casting compressed for sealingly engaging the back side of the substrate against one of the first plate and the second plate of the second molding assembly for injecting a second material into a second mold cavity of the second molding assembly to mold a second plastic casting surrounding the first plastic casting and enclosing the uncovered peripheral portion and an edge of the substrate, the second plastic casting having a peripheral outer edge; and



removing the frame, the substrate and the first and second plastic castings from the second molding assembly.

49. (Withdrawn) The method of claim 48, further comprising:  
singulating the substrate with the attached first and second plastic castings from the frame.

50. (Withdrawn) The method of claim 48, wherein molding leaves the back side of the substrate substantially uncovered.

51. (Withdrawn) The method of claim 48, further comprising applying antifiash material to the back side of the substrate prior to clamping in the second molding assembly.

52. (Withdrawn) The method of claim 51, wherein the antifiash material comprises a film.

53. (Withdrawn) The method of claim 48, wherein the substrate has peripheral edges thereabout, and the at least one connecting segment comprises at least one connecting segment on each of two opposed peripheral edges of the substrate.

54. (Withdrawn) The method of claim 48, wherein the electrical circuit includes at least one semiconductor component mounted on the circuit side of the substrate.

55. (Withdrawn) The method of claim 48, wherein the first and second plastic castings comprise epoxy resins.

56. (Withdrawn) The method of claim 48, wherein the first material and the second material comprise different resins.

57. (Withdrawn) The method of claim 48, wherein the substrate comprises a reinforced organic polymer resin.
58. (Withdrawn) The method of claim 48, further comprising subjecting the first plastic casting to a curing step prior to clamping in the second molding assembly.
59. (Withdrawn) The method of claim 48, further comprising subjecting the second plastic casting to a curing process after removal from the second molding assembly.
60. (Withdrawn) The method of claim 48, wherein the first molding assembly and the second molding assembly each comprise transfer molds.
61. (Withdrawn) The method of claim 48, wherein the at least one external connector is mounted on the back side of the substrate.
62. (Withdrawn) The method of claim 48, wherein the second molding assembly is configured to form the second plastic casting with an inner peripheral portion contiguous with the exposed surface of the first plastic casting and an outer peripheral portion displaced from the exposed surface for attachment of a label covering an interface between the first plastic casting and the second plastic casting.
63. (Withdrawn) The method of claim 48, further comprising:  
forming a notch in the second plastic casting during molding thereof configured to enclose an exposed end of a connecting segment following singulation.
64. (Withdrawn) The method of claim 63, wherein molding of the second plastic casting is performed by placing a pin in contact with the connecting segment to form the notch.

65. (Withdrawn) The method of claim 63, wherein the singulation comprises cutting the connecting segment within the notch.

66. (Withdrawn) The method of claim 49, wherein singulating comprises cutting the at least one connecting segment with a cutter die.

67. (Withdrawn) The method of claim 48, wherein the second plastic casting is formed by compressing the frame, the substrate and the first plastic casting in the second molding assembly with the second mold cavity wherein the first plastic casting is compressed for sealingly depressing the substrate to a displaced position relative to the frame.

68. (Withdrawn) The method of claim 67, wherein the second mold cavity of the second molding assembly provides for molding of laterally extending wings from a central portion of the peripheral outer edge of the second plastic casting, the wings extending outwardly beyond the peripheral outer edge.

69. (Withdrawn) The method of claim 68, wherein the displaced position provides encapsulation of the at least one connecting segment within the second plastic casting.

70. (Withdrawn) The method of claim 68, wherein singulation comprises cutting the wings and the at least one connecting segment from the second plastic casting along the peripheral outer edge thereof.

71. (Withdrawn) The method of claim 70, wherein the wings and the at least one connecting segment are cut from the second plastic casting with a saw.

72. (Withdrawn) The method of claim 68, wherein the wings and the at least one connecting segment are cut from the second plastic casting by stamping with a cutter die.

73. (Withdrawn) The method of claim 48, further comprising removing extraneous hardened plastic attached to the first plastic casting before molding of the second plastic casting.

74. (Withdrawn) The method of claim 48 further comprising removing extraneous hardened plastic attached to the second plastic casting following molding thereof.

75. (Withdrawn) A method for fabricating a card comprising:  
providing a substrate having a circuit side and a back side, the substrate having a first portion thereof having a peripheral edge separated from a second portion of the substrate by a peripheral opening spanned by at least one connecting segment between the first portion of the substrate and the second portion of the substrate;  
placing the substrate between a first plate and a second plate of a first molding assembly, the first plate and the second plate forming a first mold cavity for injecting a first material into the first mold cavity for molding a first plastic casting onto at least a portion of the circuit side of the substrate and leaving a peripheral portion of the circuit side free of the first material, the first plastic casting having an exposed surface; and  
placing the second portion of the substrate and the first plastic casting between a first plate and a second plate of a second molding assembly with at least a portion of the back side of the substrate engaging a portion of the first plate of the second molding assembly, the first plate and the second plate of the second molding assembly forming a second mold cavity for injecting a second material into the second mold cavity for molding a second plastic casting surrounding the first plastic casting and enclosing the peripheral edge of the first portion of the substrate, the second plastic casting having a peripheral outer edge.

76. (Withdrawn) The method of claim 75, further comprising:  
removing the substrate from the second molding assembly; and  
singulating the substrate.

77. (Withdrawn) The method of claim 75, wherein molding of the second plastic casting leaves the back side of the substrate substantially free of the second material.

78. (Withdrawn) The method of claim 75, further comprising:  
applying antifrash material to the back side of the substrate prior to clamping in the second molding assembly.

79. (Withdrawn) The method of claim 78, wherein the antifrash material comprises a film.

80. (Withdrawn) The method of claim 75, wherein the substrate includes at least one circuit and at least one connector.

81. (Withdrawn) The method of claim 75, wherein the first plastic casting and the second plastic casting each comprise an epoxy resin.

82. (Withdrawn) The method of claim 75, wherein the first material and the second material each comprise a different resin.

83. (Withdrawn) The method of claim 75, wherein the substrate comprises a reinforced organic polymer resin.

84. (Withdrawn) The method of claim 75, further comprising:  
subjecting the first plastic casting to curing.

85. (Withdrawn) The method of claim 75, further comprising:  
subjecting the second plastic casting to curing.

86. (Withdrawn) The method of claim 75, wherein the first molding assembly and the second molding assembly each comprise transfer molds.

87. (Withdrawn) The method of claim 75, wherein the second molding assembly is configured to form a second plastic casting having an inner peripheral portion contiguous with the exposed surface of the first plastic casting and an outer peripheral portion displaced from the exposed surface for attachment of a label covering an interface between the first plastic casting and the second plastic casting.

88. (Withdrawn) The method of claim 75, comprising:  
forming a notch in the second plastic casting to enclose an exposed end of a connecting segment.

89. (Withdrawn) The method of claim 75, further comprising:  
placing a pin in contact with the at least one connecting segment for forming a notch.

90. (Withdrawn) The method of claim 76, wherein singulating comprises cutting the at least one connecting segment.

91. (Withdrawn) The method of claim 76, wherein singulating comprises cutting the at least one connecting segment with a cutter die.

92. (Withdrawn) The method of claim 75, wherein the second plastic casting is formed by compressing the substrate in the second molding assembly with the first plastic casting compressed for sealingly depressing the substrate to a displaced position relative to the second portion of the substrate.

93. (Withdrawn) The method of claim 92, wherein the second mold cavity provides for molding of laterally extending wings from a central portion of the peripheral outer edge of the second plastic casting, the wings extending outwardly beyond the peripheral outer edge.

94. (Withdrawn) The method of claim 92, wherein the displaced position provides encapsulation of the at least one connecting segment within the second plastic casting.

95. (Withdrawn) The method of claim 93, wherein singulation comprises cutting the wings and the at least one connecting segment from the second plastic casting along the peripheral outer edge thereof.

96. (Withdrawn) A method for fabricating a card in a first molding assembly having a first plate and a second plate forming a first mold cavity and a second molding assembly having a first plate and a second plate forming a second mold cavity, the card having a substrate having a circuit side and a back side, the substrate generally separated from a surrounding frame by a peripheral opening spanned by at least one connecting segment between the substrate and the frame, the substrate having at least one electrical circuit and at least one connector for communicating between the at least one electrical circuit and an external circuit, comprising: placing the substrate and the frame between the first plate and the second plate of the first molding assembly for engaging at least portions of the first plate and at least portions of the second plate of the first molding assembly with at least portions of the substrate and the frame for injecting a first material into the first mold cavity for molding a first plastic casting onto the circuit side of the substrate and encapsulating the at least one electrical circuit while leaving a peripheral portion of the circuit side free of the first material, the first plastic casting having an exposed surface; placing the frame, substrate and first plastic casting between the first plate and the second plate of the second molding assembly, at least a portion of the exposed surface of the first plastic casting compressed for sealingly engaging a portion of the back side of the substrate against the first plate of the second molding assembly for injecting a second material into the second mold cavity for molding a second plastic casting surrounding the first plastic casting and enclosing the peripheral portion of circuit side and an edge of the substrate, the second plastic casting having a peripheral outer edge; and

singulating the substrate from the frame.

97. (Withdrawn) The method of claim 96, wherein the second molding assembly leaves the back side of the substrate substantially free of the second material.

98. (Withdrawn) The method of claim 96, further comprising:  
applying antifrash material to the back side of the substrate prior to clamping in the second molding assembly.

99. (Withdrawn) The method of claim 98, wherein the antifrash material comprises a film.

100. (Withdrawn) The method of claim 96, wherein the substrate has peripheral edges thereabout, and the at least one connecting segment comprises at least one connecting segment on each of two opposed peripheral edges of the substrate.

101. (Withdrawn) The method of claim 96, wherein the at least one electrical circuit includes at least one semiconductor component mounted on the circuit side of the substrate.

102. (Withdrawn) The method of claim 96, wherein the first plastic casting and the second plastic casting each comprise an epoxy resin.

103. (Withdrawn) The method of claim 96, wherein the first material and the second material each comprise a different resin.

104. (Withdrawn) The method of claim 96, wherein the substrate comprises a reinforced organic polymer resin.



105. (Withdrawn) The method of claim 96, further comprising:  
subjecting the first plastic casting to a curing step prior to clamping in the second molding assembly.

106. (Withdrawn) The method of claim 96, further comprising:  
subjecting the second plastic casting to a curing step after removal from the second molding assembly.

107. (Withdrawn) The method of claim 96, wherein the first molding assembly and the second molding assembly each comprise transfer molds.

108. (Withdrawn) The method of claim 96, wherein the at least one connector is mounted on the back side of the substrate.

109. (Withdrawn) The method of claim 96, wherein the second molding assembly is configured to form the second plastic casting to have an inner peripheral portion contiguous with the exposed surface of the first plastic casting and an outer peripheral portion displaced from the exposed surface for attachment of a label covering an interface between the first plastic casting and the second plastic casting.

110. (Withdrawn) The method of claim 96, comprising:  
forming a notch in the second plastic casting during molding thereof configured to enclose an exposed end of a connecting segment following singulation thereof.

111. (Withdrawn) The method of claim 110, wherein molding of the second plastic casting is performed by placing a pin in contact with the at least one connecting segment to form the notch.

112. (Withdrawn) The method of claim 110, wherein the singulation comprises cutting the connecting segment within the notch.

113. (Withdrawn) The method of claim 112, wherein the singulation further comprises cutting the connecting segment with a cutter die.

114. (Withdrawn) The method of claim 96, wherein the second plastic casting is formed by compressing the frame and the substrate in the second molding assembly with the first plastic casting compressed for sealingly depressing the substrate to a displaced position relative to the frame.

115. (Withdrawn) The method of claim 114, wherein the second mold cavity provides for molding of laterally extending wings from a central portion of the peripheral outer edge of the second plastic casting, the wings extending outwardly beyond the peripheral outer edge.

116. (Withdrawn) The method of claim 114, wherein the displaced position provides encapsulation of the at least one connecting segment within the second plastic casting.

117. (Withdrawn) The method of claim 115, wherein singulating comprises cutting the wings and the at least one connecting segment from the second plastic casting along the peripheral outer edge thereof.

118. (Withdrawn) The method of claim 117, wherein the wings and the at least one connecting segment are cut from the second plastic casting with a saw.

119. (Withdrawn) The method of claim 117, wherein the wings and the at least one connecting segment are cut from the second plastic casting by stamping with a cutter die.

120. (Withdrawn) The method of claim 96, further comprising:  
removing extraneous hardened plastic attached to the first plastic casting.

121. (Withdrawn) The method of claim 96, further comprising:  
removing extraneous hardened plastic attached to the second plastic casting.

122. (Withdrawn) A method for fabricating a plurality of semiconductor cards using a plurality of substrates in a strip having a plurality of spaced-apart substrates, the strip comprising a plurality of peripheral openings defining the plurality of substrates and a plurality of connecting segments attaching the plurality of substrates to the strip, each substrate of the plurality having at least one circuit thereon and at least one connector, the method comprising:  
mounting a card circuit on each substrate of the plurality, each card circuit comprising at least one semiconductor component and apparatus for communication between each card circuit and an external circuit;  
molding first plastic castings to the plurality of substrates using a first molding assembly comprising a plurality of mold cavities for forming a first plastic casting over each card circuit while leaving a peripheral portion of each substrate uncovered;  
molding second plastic castings to the plurality of substrates using a second molding assembly comprising a plurality of mold cavities for forming a second plastic casting encapsulating the peripheral portions of the plurality of substrates; and  
forming singulated individual semiconductor cards from the strip.

123. (Withdrawn) The method of claim 122, wherein each of the plurality of substrates has first and second planar sides, the card circuit mounted on the first side and including conductors connected to the apparatus for communication mounted on the second side.

124. (Withdrawn) The method of claim 122, wherein the apparatus for communication comprises conductive contacts.

125. (Withdrawn) The method of claim 123, wherein the first plastic casting is configured to be compressed by a first mold plate to force the second side of each substrate against a second mold plate during molding of the second plastic casting.

126. (Withdrawn) A method of fabricating a card in a first molding assembly and a second molding assembly, the card having a circuit side, a back side, and a substrate generally separated from a surrounding frame by a peripheral opening spanned by at least one connecting segment between the substrate and the frame, the substrate having an electrical circuit and at least one external connector for communicating between the electrical circuit and an external circuit, the method comprising:

placing the substrate and the frame between first and second plates of the first molding assembly for engaging at least portions of the substrate and the frame with at least portions of the first molding assembly for injecting a first material into a first mold cavity formed by the first and second plates to mold a first plastic casting onto a circuit side of the substrate and encapsulate the electrical circuit while leaving a peripheral portion of the circuit side uncovered, the first plastic casting having an exposed surface;

placing the frame, the substrate and the first plastic casting between first and second plates of the second molding assembly, the exposed surface of the first plastic casting compressed for sealingly engaging a back side of the substrate against one of the first plate and the second plate of the second molding assembly for injecting a second material into a second mold cavity of the second molding assembly to mold a second plastic casting surrounding the first plastic casting and enclosing the uncovered peripheral portion and an edge of the substrate, the second plastic casting having a peripheral outer edge; and

removing the frame, the substrate and the first and second plastic castings from the first molding assembly and the second molding assembly when molding is finished in the first molding assembly and the second molding assembly.

127. (Withdrawn) The method of claim 126, further comprising:  
singulating the substrate with the attached first and second plastic castings from the frame.

128. (Withdrawn) The method of claim 126, wherein molding leaves the back side of the substrate substantially uncovered.

129. (Withdrawn) The method of claim 126, further comprising applying antifiash material to the back side of the substrate prior to clamping in the second molding assembly.

130. (Withdrawn) The method of claim 129, wherein the antifiash material comprises a film.

131. (Withdrawn) The method of claim 126, wherein the substrate has peripheral edges thereabout, and the at least one connecting segment comprises at least one connecting segment on each of two opposed peripheral edges of the substrate.

132. (Withdrawn) The method of claim 126, wherein the electrical circuit includes at least one semiconductor component mounted on the circuit side of the substrate.

133. (Withdrawn) The method of claim 126, wherein the first and second plastic castings comprise epoxy resins.

134. (Withdrawn) The method of claim 126, wherein the first material and the second material comprise different resins.

135. (Withdrawn) The method of claim 126, wherein the substrate comprises a reinforced organic polymer resin.

136. (Withdrawn) The method of claim 126, further comprising subjecting the first plastic casting to a curing step prior to clamping in the second molding assembly.

137. (Withdrawn) The method of claim 126, further comprising subjecting the second plastic casting to a curing process after removal from the second molding assembly.

138. (Withdrawn) The method of claim 126, wherein the first molding assembly and the second molding assembly each comprise transfer molds.

139. (Withdrawn) The method of claim 126, wherein the at least one external connector is mounted on the back side of the substrate.

140. (Withdrawn) The method of claim 126, wherein the second molding assembly is configured to form the second plastic casting with an inner peripheral portion contiguous with the exposed surface of the first plastic casting and an outer peripheral portion displaced from the exposed surface for attachment of a label covering an interface between the first plastic casting and the second plastic casting.

141. (Withdrawn) The method of claim 127, further comprising:  
forming a notch in the second plastic casting during molding thereof configured to enclose an exposed end of a connecting segment following singulation.

142. (Withdrawn) The method of claim 141, wherein molding of the second plastic casting is performed by placing a pin in contact with the connecting segment to form the notch.

143. (Withdrawn) The method of claim 127, wherein singulating comprises cutting the connecting segment within the notch.

144. (Withdrawn) The method of claim 127, wherein singulating comprises cutting the at least one connecting segment with a cutter die.

145. (Withdrawn) The method of claim 126, wherein the second plastic casting is formed by compressing the frame, the substrate and the first plastic casting in the second molding assembly with the second mold cavity wherein the first plastic casting is compressed for sealingly depressing the substrate to a displaced position relative to the frame.

146. (Withdrawn) The method of claim 145, wherein the mold cavity of the second molding assembly provides for molding of laterally extending wings from a central portion of the peripheral outer edge of the second plastic casting, the wings extending outwardly beyond the peripheral outer edge.

147. (Withdrawn) The method of claim 146, wherein the displaced position provides encapsulation of the at least one connecting segment within the second plastic casting.

148. (Withdrawn) The method of claim 146, wherein singulation comprises cutting the wings and the at least one connecting segment from the second plastic casting along the peripheral outer edge thereof.

149. (Withdrawn) The method of claim 148, wherein the wings and the at least one connecting segment are cut from the second plastic casting with a saw.

150. (Withdrawn) The method of claim 146, wherein the wings and the at least one connecting segment are cut from the second plastic casting by stamping with a cutter die.

151. (Withdrawn) The method of claim 126, further comprising removing extraneous hardened plastic attached to the first plastic casting before molding of the second plastic casting.

152. (Withdrawn) The method of claim 126, further comprising removing extraneous hardened plastic attached to the second plastic casting following molding thereof.

153. (Withdrawn) A method for fabricating a card having a substrate having a circuit side and a back side, the substrate having a first portion thereof having a peripheral edge separated from a second portion of the substrate by a peripheral opening spanned by at least one connecting segment between the first portion of the substrate and the second portion of the substrate in a first molding assembly and a second molding assembly comprising:  
placing the substrate between a first plate and a second plate of the first molding assembly, the first plate and the second plate forming a first mold cavity for engaging at least a portion of the substrate by portions of the first plate and portions of the second plate for injecting a first material into the first mold cavity for molding a first plastic casting onto at least a portion of the circuit side of the substrate and leaving a peripheral portion of the circuit side free of the first material, the first plastic casting having an exposed surface; and  
placing the second portion of the substrate and the first plastic casting between a first plate and a second plate of the second molding assembly with at least a portion of the back side of the substrate engaging a portion of the first plate of the second molding assembly, the first plate and the second plate of the second molding assembly forming a second mold cavity for injecting a second material into the second mold cavity for molding a second plastic casting surrounding the first plastic casting and enclosing the peripheral edge of the first portion of the substrate, the second plastic casting having a peripheral outer edge.

154. (Withdrawn) The method of claim 153, further comprising:  
removing the substrate from the second molding assembly; and  
singulating the substrate.

155. (Withdrawn) The method of claim 153, wherein molding of the second plastic casting leaves the back side of the substrate substantially free of the second material.

156. (Withdrawn) The method of claim 153, further comprising:  
applying antifeash material to the back side of the substrate prior to clamping in the second molding assembly.



157. (Withdrawn) The method of claim 156, wherein the antifiash material comprises a film.

158. (Withdrawn) The method of claim 153, wherein the substrate includes at least one circuit and at least one connector.

159. (Withdrawn) The method of claim 153, wherein the first plastic casting and the second plastic casting each comprise an epoxy resin.

160. (Withdrawn) The method of claim 153, wherein the first material and the second material each comprise a different resin.

161. (Withdrawn) The method of claim 153, wherein the substrate comprises a reinforced organic polymer resin.

162. (Withdrawn) The method of claim 153, further comprising:  
subjecting the first plastic casting to curing.

163. (Withdrawn) The method of claim 153, further comprising:  
subjecting the second plastic casting to curing.

164. (Withdrawn) The method of claim 153, wherein the first molding assembly and the second molding assembly each comprise transfer molds.

165. (Withdrawn) The method of claim 153, wherein the second molding assembly is configured to form a second plastic casting having an inner peripheral portion contiguous with

the exposed surface of the first plastic casting and an outer peripheral portion displaced from the exposed surface for attachment of a label covering an interface between the first plastic casting and the second plastic casting.

166. (Withdrawn) The method of claim 153, comprising:  
forming a notch in the second plastic casting to enclose an exposed end of a connecting segment.

167. (Withdrawn) The method of claim 153, further comprising:  
placing a pin in contact with the at least one connecting segment for forming a notch.

168. (Withdrawn) The method of claim 154, wherein singulating comprises cutting the  
at least one connecting segment.

169. (Withdrawn) The method of claim 154, wherein singulation comprises cutting the  
at least one connecting segment with a cutter die.

170. (Withdrawn) The method of claim 153, wherein the second plastic casting is  
formed by compressing the substrate in the second molding assembly with the first plastic casting  
compressed for sealingly depressing the substrate to a displaced position relative to the second  
portion of the substrate.

171. (Withdrawn) The method of claim 170, wherein the second mold cavity provides  
for molding of laterally extending wings from a central portion of the peripheral outer edge of the  
second plastic casting, the wings extending outwardly beyond the peripheral outer edge.

172. (Withdrawn) The method of claim 170, wherein the displaced position provides  
encapsulation of the at least one connecting segment within the second plastic casting.

173. (Withdrawn) The method of claim 171, wherein singulation comprises cutting the wings and the at least one connecting segment from the second plastic casting along the peripheral outer edge thereof.